

WHAT IS CLAIMED IS

1. A chip-on-film use copper foil comprising a copper foil on at least one surface of which is provided an alloy fine roughening particle layer comprised of a copper-cobalt-nickel alloy with contents of cobalt and nickel equal to or greater than that of copper.

2. A chip-on-film use copper foil as set forth in claim 1, wherein said alloy fine roughening particle layer provided on said copper foil surface is treated for stainproof.

3. A chip-on-film use copper foil as set forth in claim 1, wherein said alloy fine roughening particle layer provided on said copper foil surface is treated by a silane coupling agent.